

# 54F/74F189 64-Bit Random Access Memory with TRI-STATE® Outputs

### **General Description**

The 'F189 is a high-speed 64-bit RAM organized as a 16-word by 4-bit array. Address inputs are buffered to minimize loading and are fully decoded on-chip. The outputs are TRI-STATE and are in the high impedance state whenever the Chip Select  $(\overline{\text{CS}})$  input is HIGH. The outputs are active only in the Read mode and the output data is the complement of the stored data.

### **Features**

- TRI-STATE outputs for data bus applications
- Buffered inputs minimize loading
- Address decoding on-chip
- Diode clamped inputs minimize ringing
- Available in SOIC, (300 mil only)

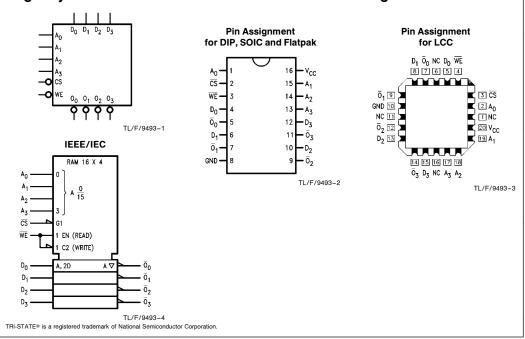
Commercial	Military	Package Number	Package Description		
74F189PC		N16E	16-Lead (0.300" Wide) Molded Dual-In-Line		
	54F189DL (Note 2)	J16A	16-Lead Ceramic Dual-In-Line		
74F189SC (Note 1)		M16A	16-Lead (0.150" Wide) Molded Small Outline, JEDEC		
74F189SJ (Note 1)		M16D	16-Lead (0.300" Wide) Molded Small Outline, EIAJ		
	54F189FL (Note 2)	W16A	16-Lead Cerpack		
	54F189LL (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C		

Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DLQB, FLQB and LLQB.

### **Logic Symbols**

### **Connection Diagrams**



## Unit Loading/Fan Out

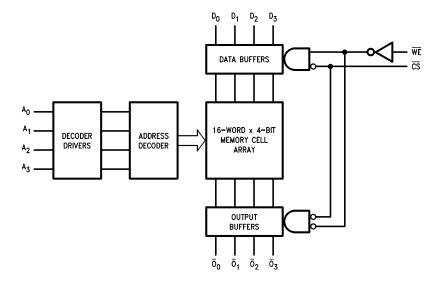
		54F/74F				
Pin Names	Description	U.L. HIGH/LOW	Input I <sub>IH</sub> /I <sub>IL</sub> Output I <sub>OH</sub> /I <sub>OL</sub>			
A <sub>0</sub> -A <sub>3</sub>	Address Inputs	1.0/1.0	20 μA/-0.6 mA			
A <sub>0</sub> -A <sub>3</sub> <del>CS</del>	Chip Select Input (Active LOW)	1.0/1.0	20 μA/ – 1.2 mA			
WE	Write Enable Input (Active LOW)	1.0/1.0	$20 \mu\text{A}/-0.6 \text{mA}$			
D <sub>0</sub> -D <sub>3</sub>	Data Inputs	1.0/1.0	20 μA/ – 0.6 mA			
$\overline{O}_0 - \overline{O}_3$	Inverted Data Outputs	150/40 (33.3)	-3.0 mA/24 mA (20 mA)			

#### **Function Table**

	Inputs CS WE		Operation	Condition of Outputs				
			Орогалон					
	L	L	Write	High Impedance				
	L	Н	Read	Complement of Stored Data				
1	Н	Χ	Inhibit	High Impedance				

$$\begin{split} \mathsf{H} &= \mathsf{HIGH} \; \mathsf{Voltage} \; \mathsf{Level} \\ \mathsf{L} &= \mathsf{LOW} \; \mathsf{Voltage} \; \mathsf{Level} \\ \mathsf{X} &= \mathsf{Immaterial} \end{split}$$

### **Block Diagram**



TL/F/9493-5

### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{lll} \mbox{Storage Temperature} & -65^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \mbox{Ambient Temperature under Bias} & -55^{\circ}\mbox{C to} + 125^{\circ}\mbox{C} \\ \mbox{Junction Temperature under Bias} & -55^{\circ}\mbox{C to} + 175^{\circ}\mbox{C} \\ \mbox{Plastic} & -55^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \end{array}$ 

V<sub>CC</sub> Pin Potential to

Voltage Applied to Output in HIGH State (with  $V_{CC} = 0V$ )

 $\begin{array}{lll} \text{Standard Output} & -0.5 \text{V to V}_{\text{CC}} \\ \text{TRI-STATE Output} & -0.5 \text{V to } +5.5 \text{V} \end{array}$ 

Current Applied to Output

in LOW State (Max) twice the rated I<sub>OL</sub> (mA)

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

## Recommended Operating Conditions

Free Air Ambient Temperature

Supply Voltage

Military + 4.5V to + 5.5V Commercial + 4.5V to + 5.5V

#### **DC Electrical Characteristics**

Symbol	Parameter -		54F/74F			Units	Vcc	Conditions	
Syllibol			Min	Тур	Max	Office	VCC	Conditions	
V <sub>IH</sub>	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Vo	oltage			-1.2	V	Min	$I_{IN} = -18 \text{ mA}$	
V <sub>OH</sub>	Output HIGH Voltage	54F 10% V <sub>CC</sub> 54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 5% V <sub>CC</sub> 74F 5% V <sub>CC</sub>	2.5 2.4 2.5 2.4 2.7 2.7			V	Min	$\begin{split} I_{OH} &= -1 \text{ mA} \\ I_{OH} &= -3 \text{ mA} \\ I_{OH} &= -1 \text{ mA} \\ I_{OH} &= -3 \text{ mA} \\ I_{OH} &= -1 \text{ mA} \\ I_{OH} &= -3 \text{ mA} \\ \end{split}$	
V <sub>OL</sub>	Output LOW Voltage	54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub>			0.5 0.5	V	Min	$I_{OL} = 20 \text{ mA}$ $I_{OL} = 24 \text{ mA}$	
I <sub>IH</sub>	Input HIGH Current	54F 74F			20.0 5.0	μΑ	Max	V <sub>IN</sub> = 2.7V	
I <sub>BVI</sub>	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μΑ	Max	V <sub>IN</sub> = 7.0V	
I <sub>CEX</sub>	Output HIGH Leakage Current	54F 74F			250 50	μΑ	Max	$V_{OUT} = V_{CC}$	
V <sub>ID</sub>	Input Leakage Test	74F	4.75			V	0.0	$I_{\text{ID}} = 1.9  \mu\text{A}$ All Other Pins Grounded	
I <sub>OD</sub>	Output Leakage Circuit Current	74F			3.75	μΑ	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded	
I <sub>IL</sub>	Input LOW Current				-0.6 -1.2	mA	Max	$V_{\text{IN}} = 0.5V \text{ (except } \overline{\text{CS}}\text{)}$ $V_{\text{IN}} = 0.5V \text{ (}\overline{\text{CS}}\text{)}$	
lozh	Output Leakage Current				50	μΑ	Max	V <sub>OUT</sub> = 2.7V	
I <sub>OZL</sub>	Output Leakage Current				-50	μΑ	Max	V <sub>OUT</sub> = 0.5V	
Ios	Output Short-Circuit Current		-60		<b>-150</b>	mA	Max	V <sub>OUT</sub> = 0V	
I <sub>ZZ</sub>	Bus Drainage Test				500	μΑ	0.0V	V <sub>OUT</sub> = 5.25V	
I <sub>CCZ</sub>	Power Supply Curren	t		37	55	mA	Max	V <sub>O</sub> = HIGH Z	

### **AC Electrical Characteristics**

Symbol	Parameter	$74F$ $T_{A} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50 \text{ pF}$			54F *T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		74F  T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units
		Min	Тур	Max	Min	Max	Min	Max	
t <sub>PLH</sub>	Access Time, HIGH or LOW $A_n$ to $\overline{O}_n$	10.0 8.0	18.5 13.5	26.0 19.0	9.0 8.0	32.0 23.0	10.0 8.0	27.0 20.0	ns
t <sub>PZH</sub>	Access Time, HIGH or LOW $\overline{\text{CS}}$ to $\overline{\text{O}}_{\text{n}}$	3.5 5.0	6.0 9.0	8.5 13.0	3.5 5.0	10.5 15.0	3.5 5.0	9.5 14.0	ns
t <sub>PHZ</sub>	Disable Time, HIGH or LOW $\overline{\text{CS}}$ to $\overline{\text{O}}_{\text{n}}$	2.0 3.0	4.0 5.5	6.0 8.0	2.0 2.5	8.0 10.0	2.0 3.0	7.0 9.0	ns
t <sub>PZH</sub>	Write Recovery Time, HIGH or LOW WE to O <sub>n</sub>	6.5 6.5	15.0 11.0	28.0 15.5	6.5 6.5	37.5 17.5	6.5 6.5	29.0 16.5	ns
t <sub>PHZ</sub>	Disable Time, HIGH or LOW $\overline{\text{WE}}$ to $\overline{\text{O}}_{\text{n}}$	4.0 5.0	7.0 9.0	10.0 13.0	3.5 5.0	12.0 15.0	4.0 5.0	11.0 14.0	ns

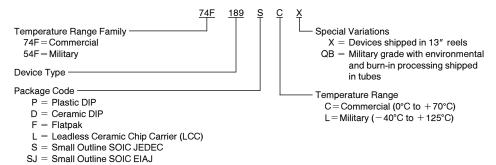
## **AC Operating Requirements**

		$74F$ $T_A = +25^{\circ}C$ $V_{CC} = +5.0V$		54	F	74F  T <sub>A</sub> , V <sub>CC</sub> = Com		Units
Symbol	Parameter			*T <sub>A</sub> , V <sub>C</sub>	<sub>C</sub> = Mil			
		Min	Max	Min	Max	Min	Max	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup Time, HIGH or LOW A <sub>n</sub> to WE	0		0		0 0		
t <sub>h</sub> (H)	Hold Time, HIGH or LOW A <sub>n</sub> to WE	2.0 2.0		2.0 2.0		2.0 2.0		ns
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup Time, HIGH or LOW D <sub>n</sub> to WE	10.0 10.0		11.0 11.0		10.0 10.0		
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold Time, HIGH or LOW D <sub>n</sub> to WE	0		2.0 2.0		0 0		ns
t <sub>S</sub> (L)	Setup Time, LOW  CS to WE	0		0		0		
t <sub>h</sub> (L)	Hold Time, LOW CS to WE	6.0		7.5		6.0		ns
t <sub>w</sub> (L)	WE Pulse Width, LOW	6.0		15.0		6.0		ns

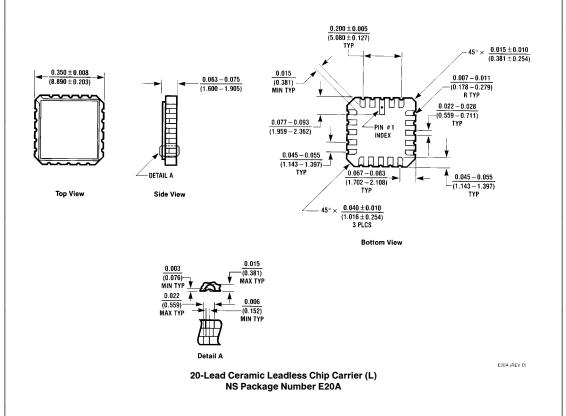
 $<sup>*</sup>T_A = -55^{\circ}C \text{ to } + 125^{\circ}C$ 

### **Ordering Information**

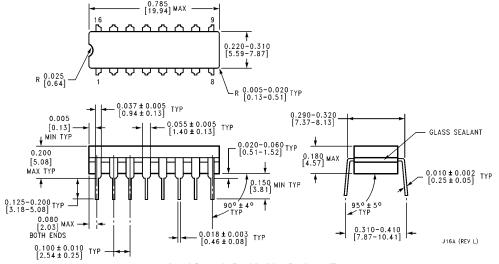
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



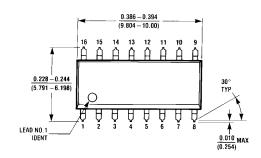
### Physical Dimensions inches (millimeters)

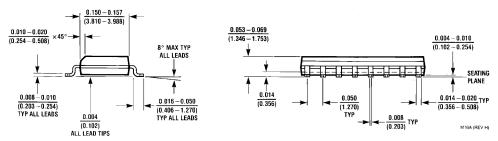




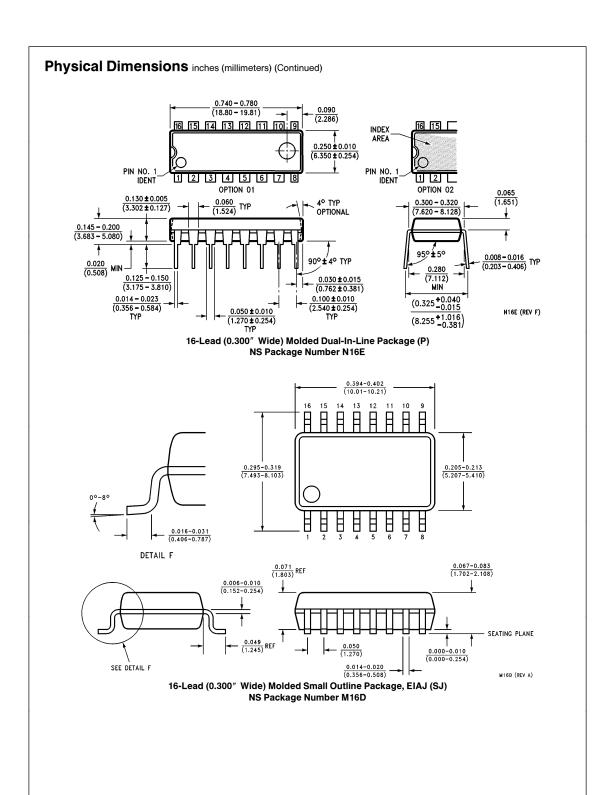


16-Lead Ceramic Dual-In-Line Package (D) NS Package Number J16A

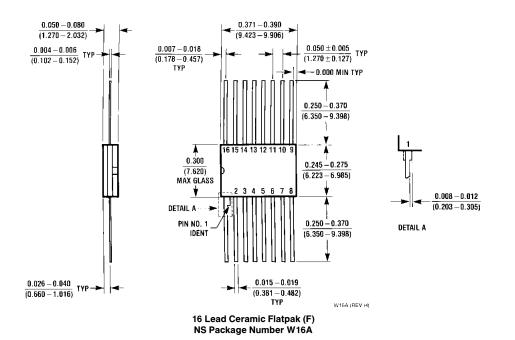




16-Lead (0.150" Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M16A



### Physical Dimensions inches (millimeters) (Continued)



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